臻鼎科技控股
Zhen Ding Tech. Holding

Zhen Ding Builds a New Blueprint of “Semiconductor + Advanced Packaging + PCB”
“One ZDT” Strategy Rides the Wave of Heterogeneous Integration to Seize the AI Industry High Ground

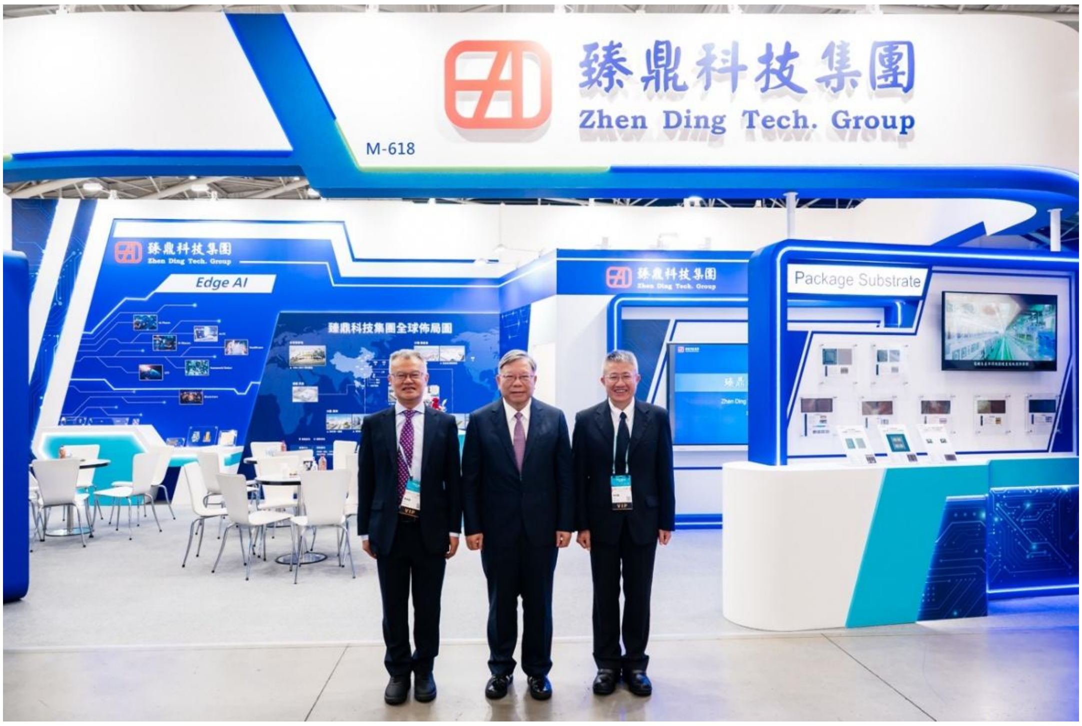
The annual PCB industry event, TPCA Show 2025, kicked off today (Oct. 22) at the Nangang Exhibition Center. Zhen Ding Tech. Group (Stock Code: 4958 showcased a full range of high-end PCBs and IC substrates under the theme of Artificial Intelligence (AI). Chairman Charles Shen pointed out that over the past 20 years, IC substrates have grown 20 times larger, increased in layer count by more than fourfold, and seen connection points surge by 300 times — resulting in overall complexity rising over 24,000 times. This evolution signifies that PCBs have transformed from mere connectors into core enablers of AI computing performance. Facing this AI- and high-performance computing-driven revolution, Zhen Ding has strengthened its “One ZDT” strategic layout, pioneering a new ecosystem of “Semiconductor + Advanced Packaging + PCB” to fuel future growth momentum.

Charles Shen emphasized that in the AI era, competition is no longer fought individually — it’s about ecosystem collaboration. Advanced packaging not only boosts chip performance but also reshapes the cooperative dynamics between the semiconductor and PCB industries. As AI and high-speed computing designs grow increasingly complex, the interrelationship among chips, packages, and substrates becomes more intertwined. From packaging architecture and interconnect design to thermal management strategies, all elements must be jointly defined at the early design stage to optimize system performance, heat dissipation, and yield — a reflection of Zhen Ding’s “top-down design” philosophy.

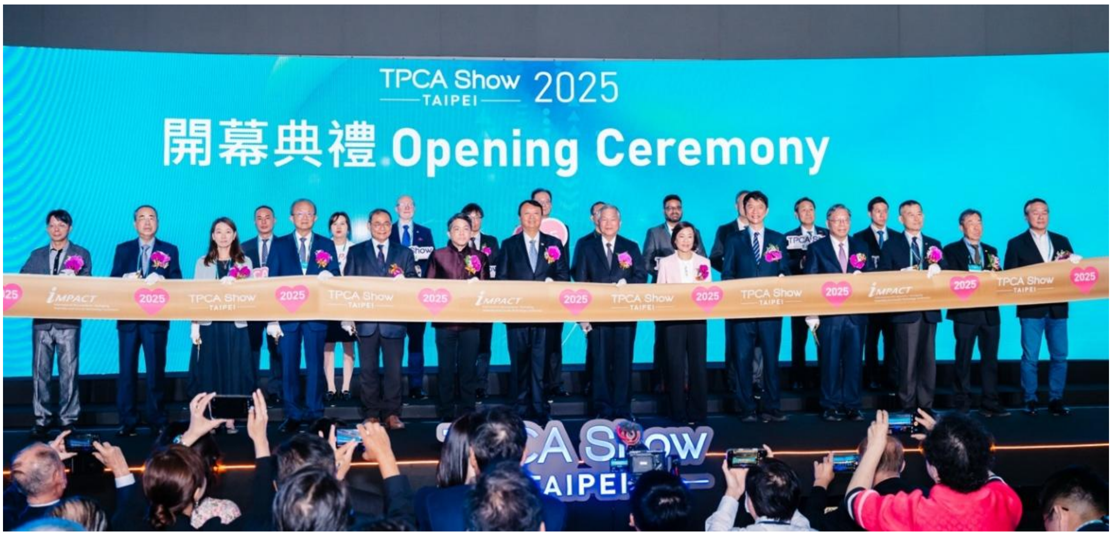
To meet the surging demand for high-end PCBs and IC substrates driven by AI applications, Zhen Ding continues to expand production capacity and invest in R&D across advanced product lines such as ABF substrates, HDI+HLC, and SLP. As the AI market rapidly grows, the company’s related revenue share has risen from 45% last year to over 70% this year. Through the cross-domain integration enabled by the “One ZDT” strategy, Zhen Ding links upstream and downstream partners to establish early-stage co-development mechanisms, putting into action the deep fusion of AI and manufacturing processes — thereby solidifying its leadership in the AI and advanced packaging revolution.

At the “TPCA Show X Business Weekly Leadership Summit”, COO DJ Lee noted that as semiconductors advance toward heterogeneous integration and advanced packaging, PCBs are evolving beyond electrical interconnects into intelligent platforms that sustain high-performance computing — “the aircraft carriers of semiconductors.” Under advanced packaging architectures, PCBs must feature finer line widths and spacing, lower signal loss, superior thermal management, and greater process integration to achieve peak system performance. Zhen Ding will continue to deepen cross-disciplinary collaboration and technological integration, driving closer ties among semiconductors, packaging, and PCBs to reshape the competitive landscape in the AI era.

Looking ahead, Zhen Ding will uphold its “One ZDT” strategy as the core of its operations, strengthening vertical integration across semiconductors, advanced packaging, and PCBs, while actively advancing smart manufacturing and digital transformation. The company will integrate AI into R&D and production workflows to enhance precision and efficiency. Shen concluded that Zhen Ding is not merely adapting to the AI wave but leading the industry’s transformation, working hand in hand with global partners to co-create technologies and elevate the value of the PCB supply chain — transitioning from connection to enablement, from design to integrated manufacturing, and becoming a driving force behind heterogeneous integration and advanced packaging development.



▲TPCA Show 2025 grandly kicked off, with key executives of Zhen Ding Technology Group gathered at the event. From left to right in the photo are General Manager James Chien, Chairman Charles Shen, and COO Lee Ting-Chuan.



▲Zhen Ding Technology Group Chairman Charles Shen attended the opening ribbon-cutting ceremony of TPCA Show 2025.

About Zhen Ding Technology Holding Limited

Zhen Ding Technology Holding Limited (Taiwan Stock Exchange: 4958) specializes in the research, development, production, and sales of a diversified range of products, including flexible printed circuit board (FPC) and surface mount assembly (SMA), substrate-likes PCBs (SLP), high-density interconnect (HDI) PCBs, high-layer-count and high-density (HLC-HDI) boards, multilayer rigid printed circuit boards (RPCB) and IC substrates (ICS). These products are widely used in end products such as computer information, consumer electronics, communications networks, automotive electronics, AI server high-speed computing, optical module and medical applications. The company offers professional one-stop shopping, full-solution services to customer worldwide. According to Prismark's global PCB industry rankings by revenue, Zhen Ding has been ranked the world's largest PCB manufacturer for eight consecutive years, from 2017 to 2024. For more detailed information, please visit the company website: www.zdtco.com.

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